



CERTIFICATE OF CONFORMITY

Certificate no.:
C560125

Initial certification date:
28 September 2022

Valid:
28 September 2022 – 27 September 2023

This is to certify that the management system of
**NEPES Corporation & NEPES Ark Cheongju 2
Campus**

587-32, Gwahaksaneop 2-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do,
28116, Republic of Korea

and the sites as mentioned in the appendix accompanying this certificate

Has been found to conform to electrostatic discharge standard:
ANSI/ESD S20.20-2021

This certificate is valid for the following scope:

**Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu
Pillar Bump, Redistribution Layer Thick Cu and Au Plating) Wafer Probing and Assembly
Process.**

The audit has been performed under the supervision of: Kyu Jun Hwang (Lead Auditor)
Client ESD Program Manager: Seung Won Lee

Place and date:
Katy, TX, 28 September 2022

For the issuing office:
DNV - Business Assurance
1400 Ravello Drive, Katy, TX, 77449-5164, USA



Chris Mauterstock
Management Representative

Lack of fulfilment of conditions as set out in the Certification Agreement may render this Certificate invalid.

ACCREDITED UNIT: DNV Business Assurance USA Inc., 1400 Ravello Drive, Katy, TX, 77449, USA - TEL: +1 281-396-1000. www.dnv.com

Appendix to Certificate

NEPES Corporation & NEPES Ark Cheongju 2 Campus

Locations included in the certification are as follows:

Site Name	Site Address	Site Scope
NEPES Corporation & NEPES Ark Cheongju 2 Campus	587-32, Gwahaksaneop 2-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, 28116, Republic of Korea	Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu Pillar Bump, Redistribution Layer Thick Cu and Au Plating) Wafer Probing and Assembly Process.
NEPES Corporation Cheongju 1 Campus	116, Gwahaksaneop 3-ro, Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, 28125, Republic of Korea	Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu Pillar Bump, Redistribution Layer Thick Cu and Au Plating) Wafer Probing and Assembly Process.
NEPES Laweh & NEPES Ark Cheongju 3 Campus	30, Nepes-ro, Cheongan-myeon, Goesan-gun, Chungcheongbuk-do, 28049, Republic of Korea	Manufacture of Semiconductor Devices including Wafer Bumping(Au Solder Plating, Cu Pillar Bump, Redistribution Layer Thick Cu and Au Plating) Wafer Probing and Assembly Process.